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**Part Number:** [0737800145](#)  
**Status:** **Active**  
**Overview:** [hdm](#)  
**Description:** 2.00mm (.079") Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 15.00mm (.591"), Pin Length 3.00mm (.118"), Solder Tail

**Documents:**

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**General**

Product Family	Backplane Connectors
Series	<a href="#">73780</a>
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	<a href="#">hdm</a>
Product Name	HDM®
Style	N/A

**Physical**

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.118 In
PC Tail Length (mm)	3.00 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.063 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C



**EU RoHS**

**ELV and RoHS  
Compliant**  
**REACH SVHC  
Contains SVHC: No**  
**Halogen-Free  
Status  
Not Reviewed**

**China RoHS**



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Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73780Series](#)

**Mates With**

HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Termination Interface: Style Through Hole

### **Electrical**

Current - Maximum per Contact	15A, 1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

### **Solder Process Data**

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

### **Material Info**

#### **Reference - Drawing Numbers**

Product Specification	PS-73780-999
Sales Drawing	SD-73780-004

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**MATERIAL NUMBER ASSIGNMENT**



**NOTES:**

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, .76 MICROMETER MINIMUM THICKNESS, SELECTIVE TIN (Sn), 2.50 MINIMUM THICKNESS ON SOLDER TAILS, NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
4. MARKINGS SHOWN FOR REFERENCE ONLY. SEE MATERIAL NUMBER ASSIGNMENT DIAGRAM FOR CORRECT NUMBER. MARKINGS TO INCLUDE MATERIAL NUMBER AND DATE CODE AND CAN BE LOCATED ANYWHERE ON PART, IN ANY ORIENTATION.
5. 73780-\*\*\*7 AND -\*\*0\* PARTS TO BE PACKAGED IN TUBES PER PK-70873-0872. ALL OTHER PARTS TO BE PACKAGED IN TUBES PER PK-70873-0900.
6. 144-CIRCUIT HDM DAUGHTERCARD STACKING MODULE WITH PRESS-FIT TAILS SHOWN FOR ILLUSTRATION PURPOSES ONLY.
7. TRUE POSITION OF PC TAILS IS INSPECTED USING GAUGE NUMBER 73727-0014.
8. MARKINGS MAY BE ORIENTED TO EITHER SIDE OF CONNECTOR.



PCB LAYOUT: COMPONENT SIDE

73780-1***	144	48.17	46.00	47.6
73780-0***	72	24.17	22.00	23.6

MATERIAL NUMBER	CIRCUIT SIZE	DIM 'A'	DIM 'B'	DIM 'C'
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UPDATE TO S.T. ONLY EC NO: UCP2010-1860 DRAWN: MELTON 2010/01/22 CHKD: DANIELLEY 05/07/08 APPR: SMILLER 2010/02/08	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$ $\nabla=0$ $\nabla=0$	mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.05 ± --- 1 PLACE ± 0.10 ± --- ANGULAR ± 2 °	MM ONLY	4:1	METRIC	
	DRAWN BY: MIBARRA CHECKED BY: BSMART APPROVED BY: SMILLER DATE: 05/07/08 DATE: 05/07/08 DATE: 2010/02/08	TITLE	SALES ASSEMBLY, HDM DAUGHTERCARD STACKING MODULE, SOLDER TAIL			
	MATERIAL NO. SD-73780-004 DOCUMENT NO. SD-73780-004 SIZE D	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MOLEX INCORPORATED THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			